

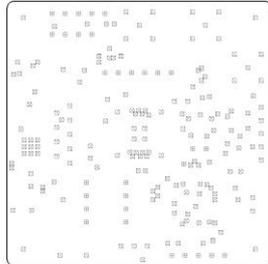
PCB Manufacturing Instructions

Project Name : **122G_003**

Revision : 003

X = 50.8 mm

Y = 50.8 mm



mils	Count
10	124
25	31
32	25
60	17
85	4
125	6

Total 207

Fabrication notes

1. Material, 4 Layer, FR-4 Glass Epoxy Laminate, 1oz copper, 0.8 mm finished thickness.
2. Manufacturing shall meet IPC-A-600 requirements.
3. All plated through holes shall have plating of 0.03 mm minimum.
4. Solder mask on Top and Bottom layers of GREEN over Bare Copper (SMOBC).
5. All exposed pads to be HOT Air Solder Levelled.
6. NO SILKSCREEN on either side.
7. There shall be no stray metal particles on the PCB or Circuits.
8. ALL Boards shall be electrically tested for opens and shorts.
9. ALL attached drawings are viewed from the Top side view.
10. ALL CAD dimensions are in Inches.
11. Route edge of PCB in accordance with the Mechanical Outline

Layer order

Top Solder Mask
Top Layer
FR-4
Ground Plane
FR-4
Mid1 Layer
FR-4
Bottom Layer
Bottom Solder Mask